

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D@25^{\circ}C$
1200V	20m Ω @15V	101A
	16m Ω @18V	
	15m Ω @20V	

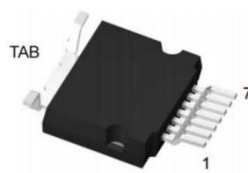
Feature

- Wide bandgap SiC MOSFET technology
- Low On-Resistance with High Blocking Voltage
- Low Capacitances with High-Speed switching
- Low reverse recovery(Qrr)

Application

- Switch mode power supplies
- Renewable energy
- Motor drives
- High voltage DC/DC converters

Package

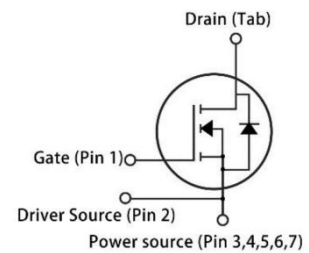


T2PAK

Marking



Circuit diagram



Absolute maximum ratings ($T_c=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Condition	Value	Unit
Drain-Source Voltage	V_{DSmax}	$V_{GS} = 0V, I_D = 100\mu A$	1200	V
Gate-Source Voltage	V_{GSmax}	AC ($f > 1 \text{ Hz}$)	-10/+25	V
Recommend Gate-Source Voltage	V_{GSop}	Static	-4/+15 -4/+18	V
Continuous Drain Current	I_D	$V_{GS} = 15V, T_c=25^{\circ}C$ $V_{GS} = 18V, T_c=25^{\circ}C$	101	A
	I_D	$V_{GS} = 15V, T_c=100^{\circ}C$ $V_{GS} = 18V, T_c=100^{\circ}C$	72	A
Pulsed Drain Current	$I_{DM (pluse)}$	Pulse with t_p limited by T_{jmax} at 1 ms Pulse with t_p limited by T_{jmax} at 100 μs	232 494	A
Power Dissipation	P_D	$T_c=25^{\circ}C$	428	W
Thermal Resistance (Typ)	$R_{\theta JC}$	Junction-to-Case	0.35	$^{\circ}C/W$
Junction Temperature	T_J		-55~ +175	$^{\circ}C$
Storage Temperature	T_{STG}		-55~ +175	$^{\circ}C$

Electrical characteristics (T_j=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =100μA	1200			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =1200V,V _{GS} = 0V,T _J =150°C			50	μA
Gate-Source leakage current	I _{GSS}	V _{GS} =15V, V _{DS} = 0V			250	nA
		V _{GS} =18V, V _{DS} = 0V				
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =23mA		2.9		V
		V _{DS} =V _{GS} , I _D =23mA ,T _J =175°C		2.0		
Drain-source on-resistance	R _{DS(on)}	V _{GS} =15V, I _D =75A		20		mΩ
		V _{GS} =18V, I _D =75A		16	24	
		V _{GS} =20V, I _D =75A		15		
		V _{GS} =15V, I _D =75A ,T _J =175°C		36		
		V _{GS} =18V, I _D =75A ,T _J =175°C		34		
		V _{GS} =20V, I _D =75A ,T _J =175°C		33		
Dynamic characteristics ³⁾						
Input Capacitance	C _{iss}	V _{DS} =1000V,V _{GS} =0V,f =100 kHz V _{AC} = 25mV		5806		pF
Output Capacitance	C _{oss}			216		
Reverse Transfer Capacitance	C _{rss}			14		
Total Gate Charge	Q _g	V _{DS} =800V,I _D =75A V _{GS} =-4V/18V, V _{GS} =-4V/15V		235		nC
Gate-Source Charge	Q _{gs}			73.6		
Gate-Drain Charge	Q _{gd}			69.8		
Source-Drain Diode characteristics						
Diode Forward Current	I _S	V _{GS} =-4V, T _C =25°C		146		A
Diode Forward voltage	V _{SD}	V _{GS} =-4V, I _{SD} = 37.5A		3.9		V
		V _{GS} =-4V, I _{SD} = 37.5A,T _J =150°C		3.3		

Typical Characteristics

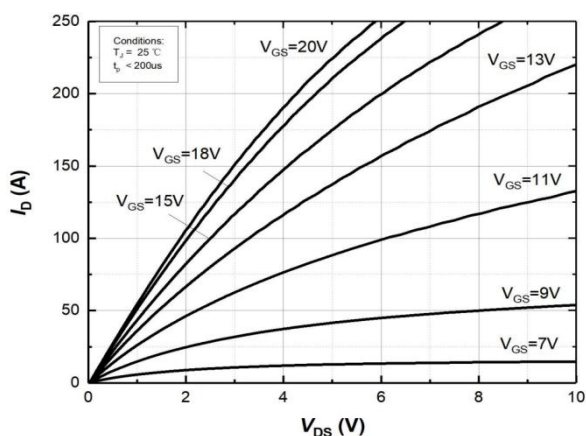


Figure 1. Output characteristics at $T_j=25^\circ\text{C}$

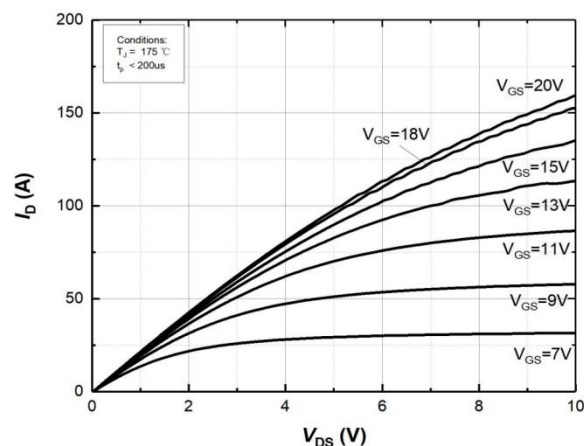


Figure 2. Output characteristics at $T_j=175^\circ\text{C}$

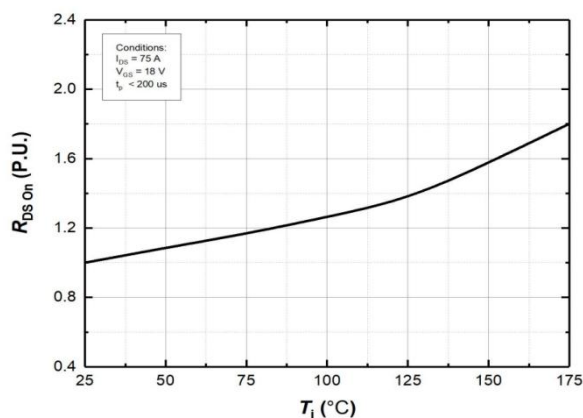


Figure 3. Normalized On-Resistance vs. Temperature

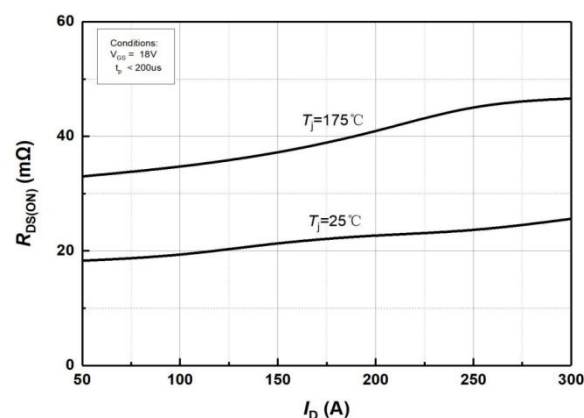


Figure 4. On-Resistance vs. Drain current for Various Temperature

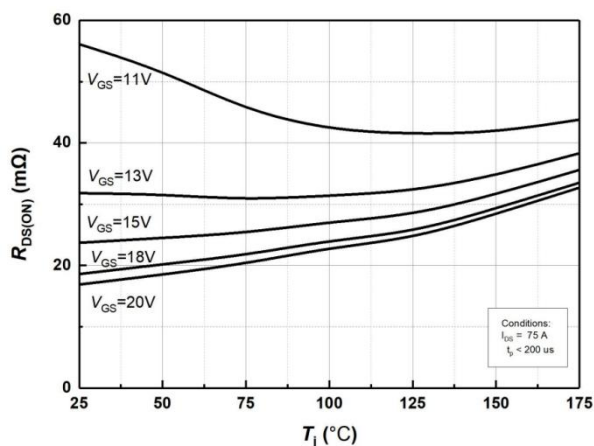


Figure 5. On-Resistance vs. Temperature for Various Gate Voltage

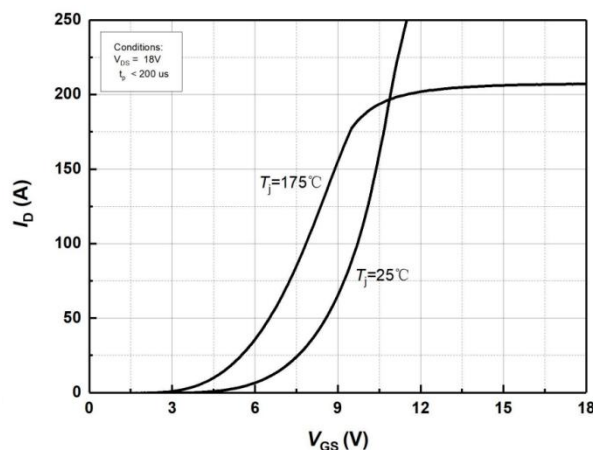


Figure 6. Transfer Characteristics for Various Junction Temperatures

Typical Characteristics

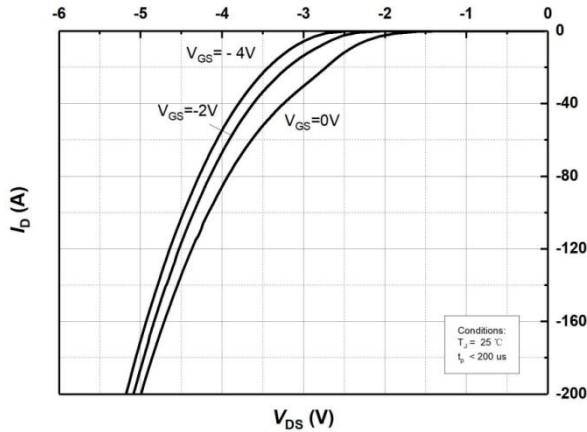


Figure 7. Body Diode Characteristics at Tj=25°C

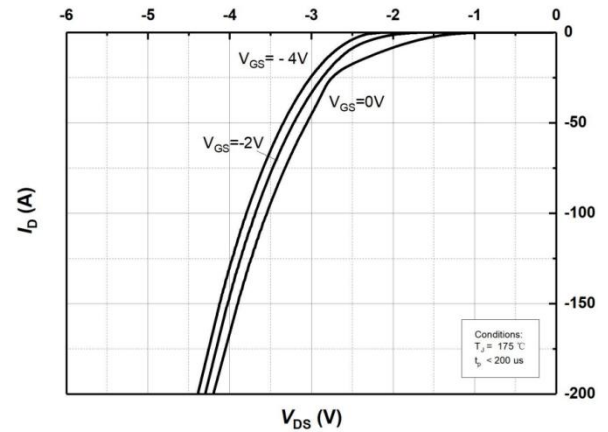


Figure 8. Body Diode Characteristics at Tj=175°C

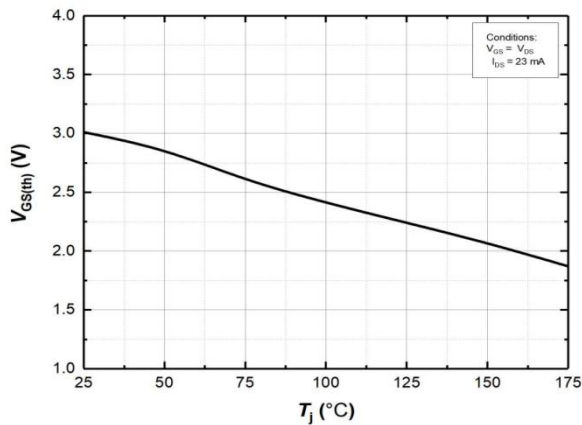


Figure 9. Threshold Voltage vs. Temperature

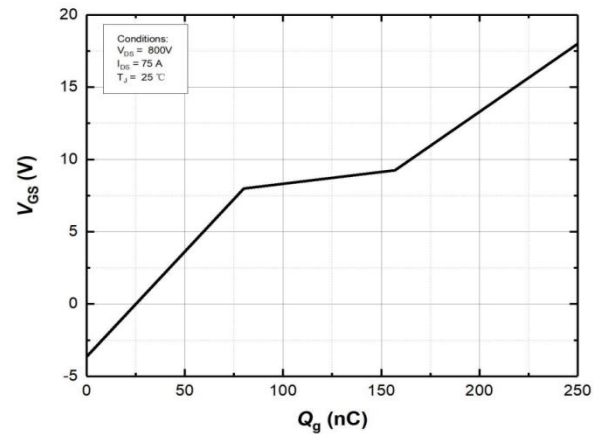


Figure 10. Gate Charge Characteristics

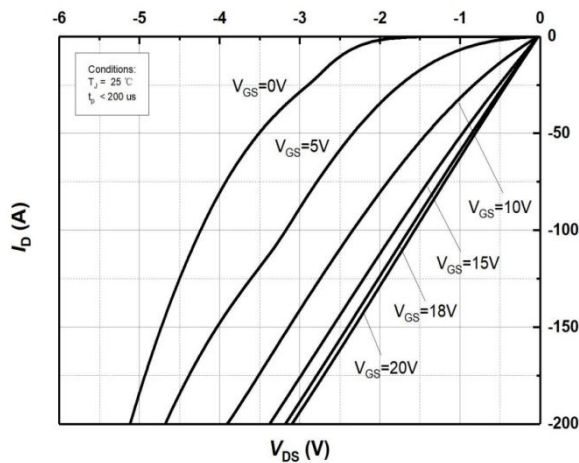


Figure 11. 3rd Quadrant Characteristic at Tj=25°C

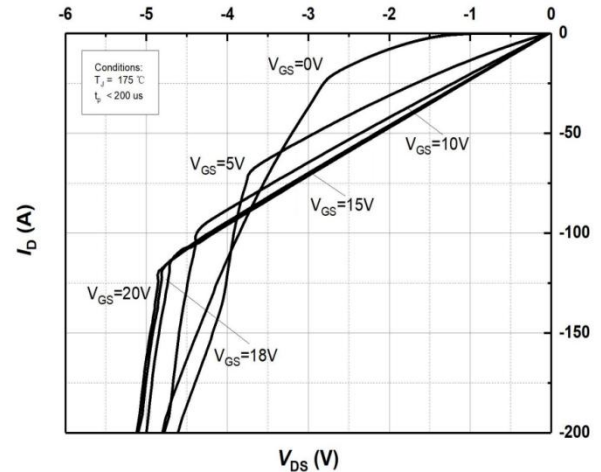


Figure 12. 3rd Quadrant Characteristic at Tj=175°C

Typical Characteristics

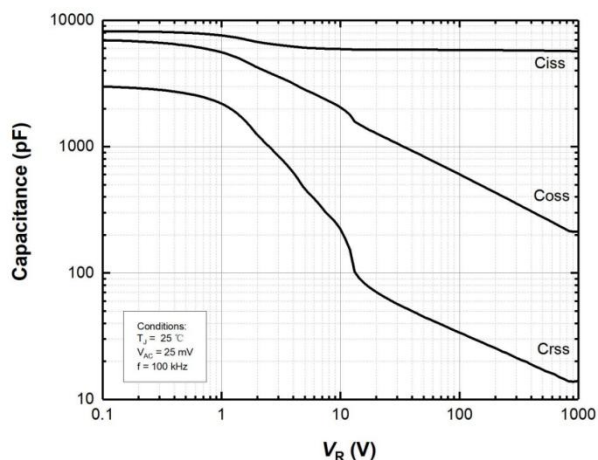


Figure 13. Capacitances vs. Drain-Source Voltage (0 – 1000V)

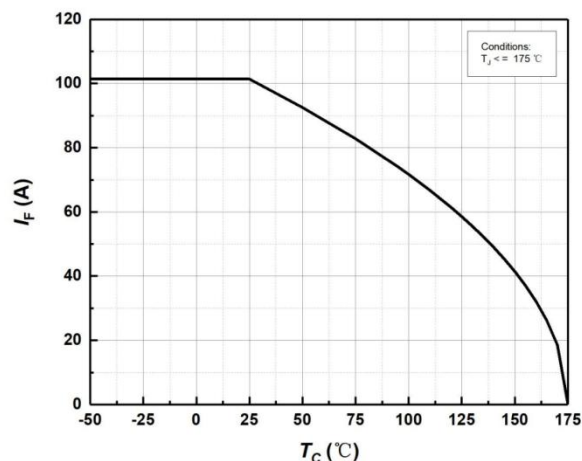


Figure 14. Continuous Drain Current Derating vs Case Temperature

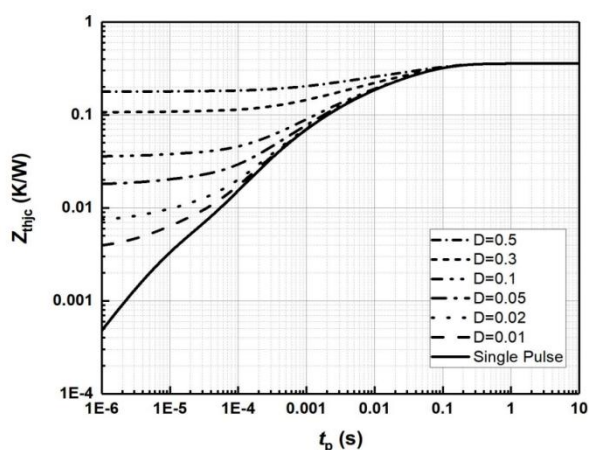


Figure 15. Transient Thermal Impedance (Junction – Case)

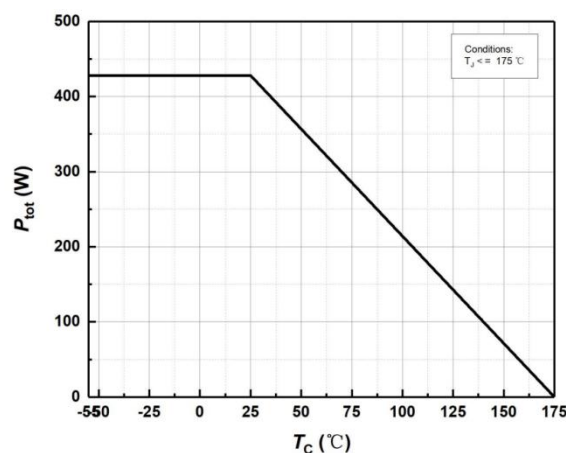


Figure 16. Maximum Power Dissipation Derating vs. Case Temperature

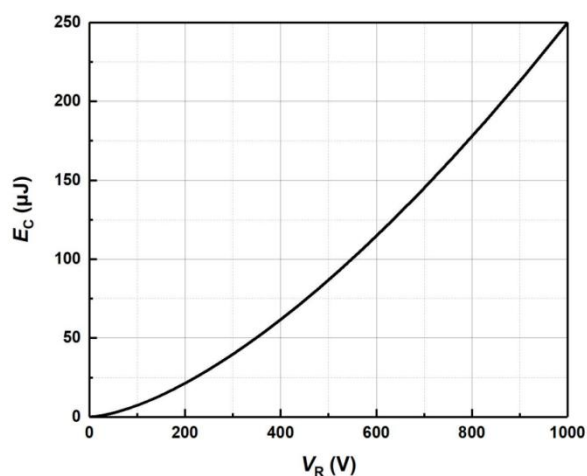


Figure 17. Output Capacitor Stored Energy

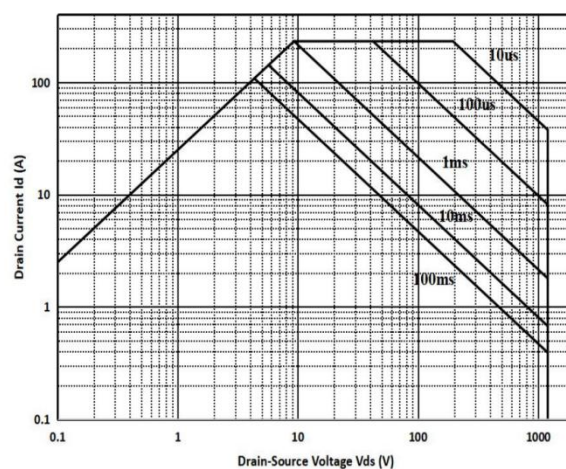
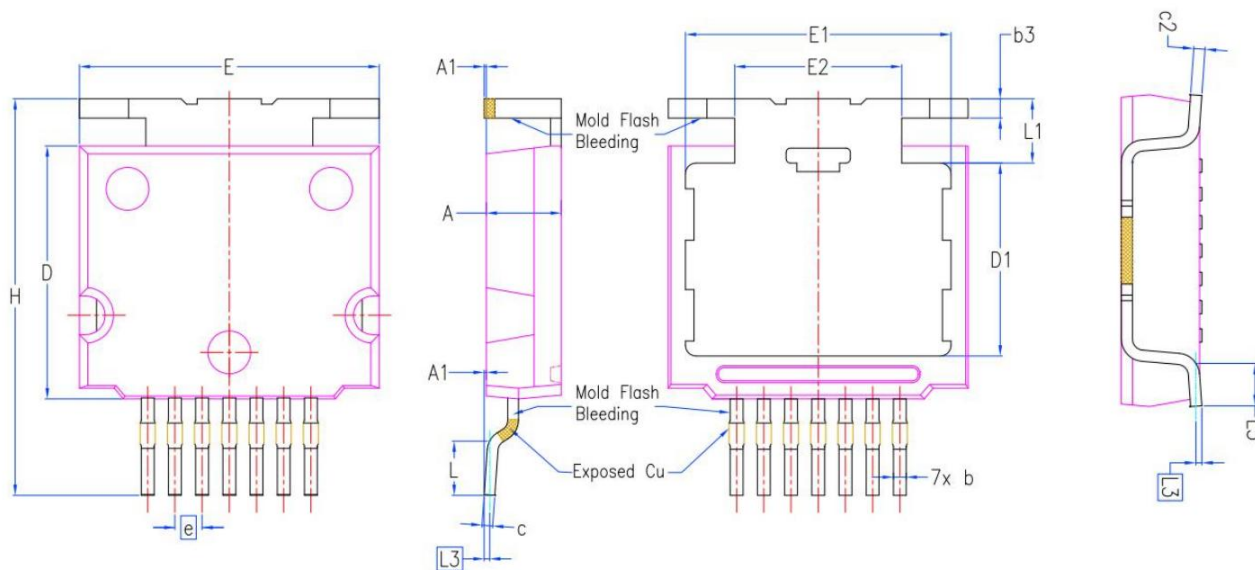


Figure 18. Safe Operating Area

T2PAK Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	3.400	3.600	0.134	0.142
A1	0.000	0.250	0.000	0.010
b	0.500	0.700	0.020	0.028
b3	0.800	1.000	0.031	0.039
c	0.400	0.600	0.016	0.024
c2	0.400	0.600	0.016	0.024
D	11.700	11.900	0.461	0.469
D1	8.800	9.100	0.346	0.358
E	13.900	14.100	0.547	0.555
E1	12.300	12.500	0.484	0.492
E2	7.750	7.850	0.305	0.309
e	1.270 BSC		0.050 BSC	
H	18.000	19.000	0.709	0.748
L	2.300	2.750	0.091	0.108
L1	3.050 BSC		0.120 BSC	
L3	0.260 BSC		0.010 BSC	
L5	1.700	2.150	0.067	0.085